

Cypress Semiconductor Product Qualification Report

QTP# 063108 VERSION 1.0
October 2006

CY28547	Clock Generator for Intel® CK410M/CK505
R52T-3 Technology, Fab4	

CYPRESS TECHNICAL CONTACT FOR QUALIFICATION DATA:

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TECHNOLOGY QUALIFICATION HISTORY

Qual Report	Description of Qualification Purpose	Date Comp
024604	R52T-3 Technology Process Derivative Qual	May 03
040903	New Device B30M (CY28437) Base Die in R52T-3 Technology	Feb 05
063108	CY28547 Mask/Bond Option from qualified B30M Base Die in R52T-3 Technology	Oct 06

PRODUCT DESCRIPTION (for qualification)	
Qualification Purpose: CY28547-5 Mask Option from qualified B30M Base Die in R52T-3 Technology	
Marketing Part #:	CY28547
Device Description:	3.3V, Clock Generator for Intel® CK410M/CK505 available in 72-Pin QFN
Cypress Division:	Cypress Semiconductor Corporation –Consumer & Computation Division (CCD)

TECHNOLOGY/FAB PROCESS DESCRIPTION - R52T-3			
Number of Metal Layers:	3	Metal Composition:	Metal 1: 500Å TiW / 6000Å Al / 500Å TiW Metal 2: 500Å TiW / 6000Å Al / 500Å TiW Metal 3: 300Å Ti / 8000Å Al / 300Å TiW
Passivation Type and Materials:	1000Å SiO ₂ / 9000Å Si ₃ N ₄		
Generic Process Technology/Design Rule (μ-drawn):	CMOS – Triple Metal, 0.25μm		
Gate Oxide Material/Thickness (MOS):	SiO ₂ , 55Å		
Name/Location of Die Fab (prime) Facility:	Cypress Semiconductor -- Bloomington, MN		
Die Fab Line ID/Wafer Process ID:	Fab4/R52T-3		

PACKAGE AVAILABILITY

PACKAGE	ASSEMBLY SITE FACILITY
72-Pin QFN	KOREA-L

MAJOR PACKAGE INFORMATION USED IN THIS QUALIFICATION	
Package Designation:	LY72
Package Outline, Type, or Name:	72-Lead QFN
Mold Compound Name/Manufacturer:	Sumitomo G700FG
Mold Compound Flammability Rating:	V-O per UL94
Oxygen Rating Index:	NA
Lead Frame Material:	Copper
Lead Finish, Composition / Thickness:	NiPdAu
Die Backside Preparation Method/Metallization:	Backgrind
Die Separation Method:	Saw
Die Attach Supplier:	Ablestik
Die Attach Material:	Ablebond 8290
Die Attach Method:	Epoxy
Bond Diagram Designation	001-05918
Wire Bond Method:	Thermosonic
Wire Material/Size:	Au. 1.0mil
Thermal Resistance Theta JA °C/W:	22°C/W
Package Cross Section Yes/No:	N/A
Assembly Process Flow:	001-05842
Name/Location of Assembly (prime) facility:	Korea-L
MSL Level	3
Reflow Profile	260C

ELECTRICAL TEST / FINISH DESCRIPTION	
Test Location:	CML-R

RELIABILITY TESTS PERFORMED PER SPECIFICATION REQUIREMENT

Stress/Test	Test Condition (Temp/Bias)	Result P/F
High Temperature Operating Life Early Failure Rate	Dynamic Operating Condition, Vcc Max = 3.8V, 125°C	P
High Temperature Operating Life Latent Failure Rate	Dynamic Operating Condition, Vcc Max = 3.8V, 125°C	P
High Accelerated Saturation Test (HAST)	130°C, 3.63V, 85%RH Precondition: JESD22 Moisture Sensitivity MSL 3 192 Hrs, 30C/60%RH+3IR-Reflow, 220°C+0, -5°C	P
Temperature Cycle	MIL-STD-883C, Method 1010, Condition C, -65°C to 150°C Precondition: JESD22 Moisture Sensitivity MSL 3 192 Hrs, 30C/60%RH+3IR-Reflow, 220°C+0, -5°C Precondition: JESD22 Moisture Sensitivity MSL 1 168 Hrs, 85C/85%RH+3IR-Reflow, 260°C+0, -5°C	P
Pressure Cooker	121°C, 100%RH, 15 Psig Precondition: JESD22 Moisture Sensitivity MSL 3 192 Hrs, 30C/60%RH+3IR-Reflow, 220°C+0, -5°C Precondition: JESD22 Moisture Sensitivity MSL 1 168 Hrs, 85C/85%RH+3IR-Reflow, 260°C+0, -5°C	P
Electrostatic Discharge Human Body Model (ESD-HBM)	2,200V JESD22, Method A114-B	P
Electrostatic Discharge Human Body Model (ESD-HBM)	2,200V MIL-STD-883, Method 3015.7	P
Electrostatic Discharge Charge Device Model (ESD-CDM)	500V Cypress Spec. 25-00020	P
Acoustic Microscopy	Cypress Spec. 25-00104	P
Static Latch-up	125C, ± 200mA/± 300mA Cypress Spec. 01-00081	P

RELIABILITY FAILURE RATE SUMMARY

Stress/Test	Device Tested/ Device Hours	# Fails	Activation Energy	Thermal AF ⁴	Failure Rate
High Temperature Operating Life Early Failure Rate	4,377 Devices	0	N/A	N/A	0 PPM
High Temperature Operating Life ^{1,2} Long Term Failure Rate	547,000 DHRs	0	0.7	55	30 FITs

¹ Assuming an ambient temperature of 55°C and a junction temperature rise of 15°C.

² Chi-squared 60% estimations used to calculate the failure rate.

³ Thermal Acceleration Factor is calculated from the Arrhenius equation

$$AF = \exp \left[\frac{E_A}{k} \left[\frac{1}{T_2} - \frac{1}{T_1} \right] \right]$$

where:

E_A = The Activation Energy of the defect mechanism.

k = Boltzmann's constant = 8.62×10^{-5} eV/Kelvin.

T_1 is the junction temperature of the device under stress and T_2 is the junction temperature of the device at use conditions.

Reliability Test Data

QTP #: 024604

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
STRESS: ACOUSTIC-, MSL3							
CY6981-BA (7C6981A)	4223346	610243127/3004	TAIWN-G	COMP	18	0	
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-EARLY FAILURE RATE (125C, 3.8V, Vcc Max)							
CY6981-BA (7C6981A)	4147861	610221501/2/27521	TAIWN-G	96	1342	0	
CY6981-BA (7C6981A)	4238026	610250542	TAIWN-G	96	1020	0	
CY6981-BA (7C6981A)	4223346	610243127/3004/7	TAIWN-G	96	1015	0	
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE (125C, 3.8V, Vcc Max)							
CY6981-BA (7C6981A)	4147861	610221501/2	TAIWN-G	168	182	0	
CY6981-BA (7C6981A)	4147861	610221501/2	TAIWN-G	500	182	0	
CY6981-BA (7C6981A)	4147861	610221501/2	TAIWN-G	1000	182	0	
CY6981-BA (7C6981A)	4223346	610243127/3004	TAIWN-G	168	182	0	
CY6981-BA (7C6981A)	4223346	610243127/3004	TAIWN-G	500	182	0	
CY6981-BA (7C6981A)	4223346	610243127/3004	TAIWN-G	1000	180	0	
CY6981-BA (7C6981A)	4238026	610250542	TAIWN-G	168	368	0	
CY6981-BA (7C6981A)	4238026	610250542	TAIWN-G	500	368	0	
STRESS: ESD-CHARGE DEVICE MODEL (500V)							
CY6981-BA (7C6981A)	4147861	610221501/2/2752	TAIWN-G	COMP	9	0	
CY6981-BA (7C6981A)	4223346	610243127/3004	TAIWN-G	COMP	9	0	
ESD-HUMAN BODY CIRCUIT PER MIL STD 883, METHOD 3015 (2,200V)							
CY6981-BA (7C6981A)	4147861	610221501/2/2752	TAIWN-G	COMP	9	0	
CY6981-BA (7C6981A)	4223346	610243127/3004	TAIWN-G	COMP	9	0	
STRESS: STATIC LATCH-UP TESTING (125C, 10V, +/-300mA)							
CY6981-BA (7C6981A)	4147861	610221501/2/2752	TAIWN-G	COMP	3	0	
CY6981-BA (7C6981A)	4238026	610250542	TAIWN-G	COMP	3	0	
STRESS: PRESSURE COOKER TEST, (121C, 100%RH), 15 Psig, PRE COND 192 HR 30C/60%RH, MSL3							
CY6981-BA (7C6981A)	4147861	610221501/2/2752	TAIWN-G	168	50	0	
CY6981-BA (7C6981A)	4223346	610243127/3004	TAIWN-G	168	48	0	
CY6981-BA (7C6981A)	4223346	610243127/3004	TAIWN-G	288	48	0	
CY6981-BA (7C6981A)	4238026	610250542	TAIWN-G	168	48	0	
CY6981-BA (7C6981A)	4238026	610250542	TAIWN-G	288	48	0	

Reliability Test Data

QTP #: 024604

<i>Device</i>	<i>Fab Lot #</i>	<i>Assy Lot #</i>	<i>Assy Loc</i>	<i>Duration</i>	<i>Samp</i>	<i>Rej</i>	<i>Failure Mechanism</i>
STRESS: HI-ACCEL SATURATION TEST (130C, 85%RH, 3.63V), PRE COND 192 HR 30C/60%RH, MSL3							
CY6981-BA (7C6981A)	4147861	610221501/2/2752	TAIWN-G	128	50	0	
CY6981-BA (7C6981A)	4223346	610243127/3004	TAIWN-G	128	47	0	
STRESS: TC COND. C -65C TO 150C, PRE COND 192 HRS 30C/60%RH, MSL3							
CY6981-BA (7C6981A)	4147861	610221501/2/2752	TAIWN-G	300	50	0	
CY6981-BA (7C6981A)	4147861	610221501/2/2752	TAIWN-G	500	50	0	
CY6981-BA (7C6981A)	4147861	610221501/2/2752	TAIWN-G	1000	50	0	
CY6981-BA (7C6981A)	4223346	610243127/3004	TAIWN-G	300	48	0	
CY6981-BA (7C6981A)	4223346	610243127/3004	TAIWN-G	500	48	0	
CY6981-BA (7C6981A)	4223346	610243127/3004	TAIWN-G	1000	48	0	
CY6981-BA (7C6981A)	4238026	610250542	TAIWN-G	300	48	0	
CY6981-BA (7C6981A)	4238026	610250542	TAIWN-G	500	48	0	
CY6981-BA (7C6981A)	4238026	610250542	TAIWN-G	1000	48	0	

Reliability Test Data

QTP #: 040903

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
STRESS: ESD-CHARGE DEVICE MODEL, 500V							
CY28437OXCT (7C828437A)	4444247	610463705	CML-R	COMP	9	0	
STRESS: ESD-HUMAN BODY CIRCUIT PER JESD22, METHOD A114-B, 2,200V							
CY28437OXCT (7C828437A)	4444247	610463705	CML-R	COMP	9	0	
STRESS: ESD-HUMAN BODY CIRCUIT PER MIL STD 883, METHOD 3015, 2,200V							
CY28437OXCT (7C828437A)	4444247	610463705	CML-R	COMP	3	0	
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-EARLY FAILURE RATE, 125C, 3.8V, Vcc Max							
CY28437OXCT (7C828437A)	4444247	610463705	CML-R	96	442	0	
CY28437OXCT (7C828437A)	4444247	610463737	CML-R	96	260	0	
CY28437OXCT (7C828437A)	4444247	610463736	CML-R	96	298	0	
STRESS: PRESSURE COOKER TEST, (121C, 100%RH), 15 Psig, PRE COND 168 HR 85C/85%RH, MSL1							
CY28437OXCT (7C828437A)	4444247	610463705	CML-R	168	45	0	
STRESS: STATIC LATCH-UP TESTING (125C, 8.48V, +/-300mA)							
CY28437OXCT (7C828437A)	4444247	610463705	CML-R	COMP	3	0	
STRESS: TC COND. C -65C TO 150C, PRE COND 168 HR 85C/85%RH, MSL1							
CY28437OXCT (7C828437A)	4444247	610463705	CML-R	300	45	0	

Reliability Test Data

QTP #: 063108

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
STRESS: ESD-CHARGE DEVICE MODEL, 500V							
CY28547LFXC (7C828547C)	4615730	610638706	KOREA-L	COMP	9	0	
STRESS: ESD-HUMAN BODY CIRCUIT PER JESD22, METHOD A114-B, 2,200V							
CY28547LFXC (7C828547C)	4615730	610638706	KOREA-L	COMP	9	0	
STRESS: ESD-HUMAN BODY CIRCUIT PER MIL STD 883, METHOD 3015, 2,200V							
CY28547LFXC (7C828547C)	4615730	610638706	KOREA-L	COMP	3	0	
STRESS: STATIC LATCH-UP TESTING (125C, 6.5V, +/-200mA)							
CY28547LFXC (7C828547C)	4615730	610638706	KOREA-L	COMP	3	0	